

## **ABSTRACT**

### **DEVICE CHIP PACKAGE MANUFACTURING METHOD**

Disclosed herein is a device chip package manufacturing method including a cutting step of forming cut grooves having a depth reaching a finished thickness of device chips by cutting a device wafer from a top surface of the device wafer along streets by a cutting blade, a cut groove inclination state detecting step of detecting an inclination state of the cut grooves, a sealing resin layer forming step of forming a sealing resin layer coating the top surface and the cut grooves of the device wafer by supplying a sealing resin to the top surface of the device wafer, and a laser processing step of dividing the device wafer into individual chips and forming device chip packages by applying a laser beam having a wavelength absorbable by the sealing resin layer along the cut grooves of the device wafer held by a chuck table.

(Figure 10)